

## GENERAL DESCRIPTION

The ft2820 is a 4W boosted Class-G audio power amplifier based upon a proprietary **Dual-Pump™** topology with automatic level control (ALC). It operates from 3V to 5.5V supply. When operating with a 4.2V supply voltage, it is capable of driving a 4Ω speaker load at a continuous average output of 4W with 10% THD+N. Its high efficiency, up to 82%, helps extend battery life for portable device applications.

In ft2820, the power supply rail for the amplifier's output stage is internally boosted and regulated at 6V by an adaptive charge pump based upon the **Dual-Pump™** topology, thus allowing for a much louder audio output than a stand-alone one directly connected to the battery. It makes ft2820 an ideal audio solution for portable devices that are powered by a single-cell lithium battery while requiring higher audio loudness.

The ft2820 features ALC on the audio output signals, which detects the output clipping caused by the over-level input signal and automatically adjusts the voltage gain of the amplifier to eliminate the clipping while maintaining the maximally-allowed dynamic range of the audio output signals. The ALC also eliminates the output clipping due to low battery supply voltage.

## FEATURES

- Proprietary **Dual-Pump™** topology
- Filterless Class-G operation with an integrated charge pump
- Automatic level control to eliminate output clipping
- Integrated lowpass filter for out-of-band noise rejection
- Maximum output power: 4W (VDD=4.2V, RL=4Ω, THD+N=10%, ALC Off)
- Constant output power: 3.3W (VDD=4.2V, RL=4Ω, THD+N=0.5%, ALC On)
- High power efficiency up to 82%
- Low THD+N: 0.05% (VDD=3.6V, f=1kHz, RL=4Ω, Po=1W)
- ALC dynamic range: 10.5dB
- Low quiescent current: 2.7mA @ VDD=3.6V
- High PSRR: 75dB @ 217Hz
- Two gain settings: 24.1/27.6dB
- One-wire pulse control to set operating mode and voltage gain
- Auto-recovering short-circuit protection
- Available in TSSOP-20L package

## APPLICATIONS

- Portable Speakers
- MID
- Mobile Phones

## APPLICATION CIRCUIT

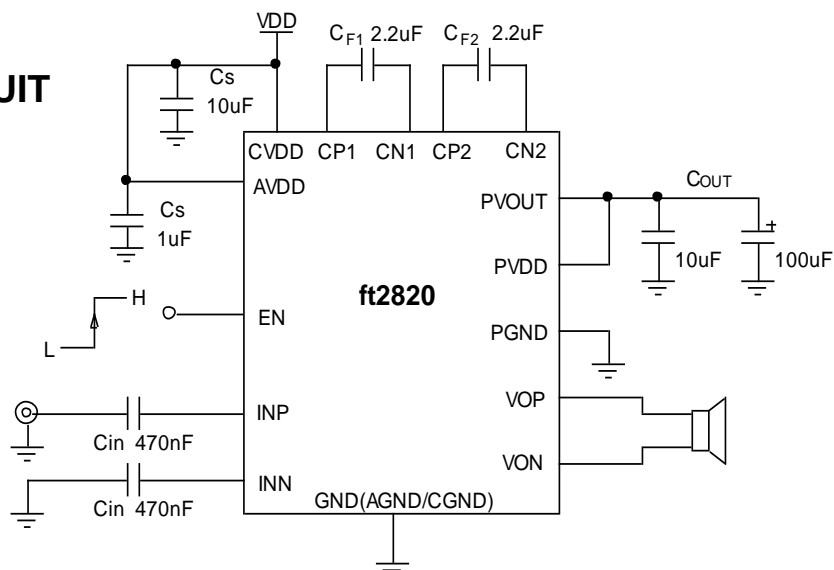
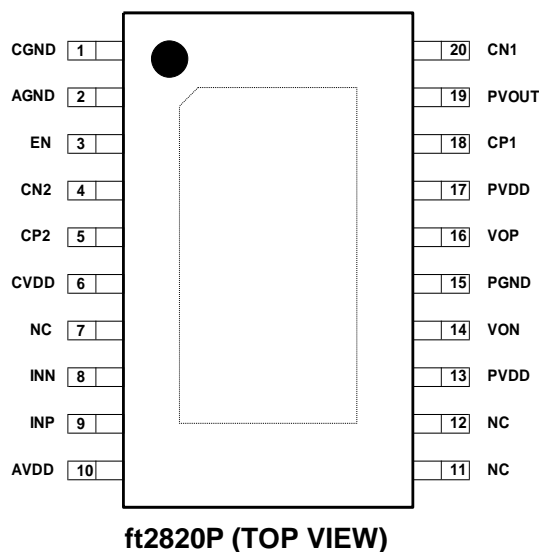


Figure 1: Typical Application Circuit Diagram

## PIN CONFIGURATION AND DESCRIPTION



SYMBOL	PIN NUMBER	I/O	DESCRIPTION
EN	3	I	Chip enable & one-wire pulse control.
CN2	4	O	Flying capacitor CF2 negative terminal.
CP2	5	O	Flying capacitor CF2 positive terminal.
CVDD	6	P	Power supply for the charge pump.
INN	8	I	Negative audio input terminal.
INP	9	I	Positive audio input terminal.
AVDD	10	P	Analog power supply.
PVDD	13, 17	P	Power supply rail for the Class-D amplifier output stage. It must be externally shorted to PVOUT.
VON	14	O	Negative BTL audio output.
PGND	15	G	Ground for the Class-D amplifier output stage.
VOP	16	O	Positive BTL audio output.
CP1	18	O	Flying capacitor CF1 positive terminal.
PVOUT	19	O	Boosted voltage output generated by the charge pump. It must be externally shorted to PVDD on the system board.
CN1	20	O	Flying capacitor CF1 negative terminal.
CGND	1	G	Ground for the charge pump.
AGND	2	G	Analog ground.
NC	7, 11, 12	-	No internal connection.

## ORDERING INFORMATION

PART NUMBER	TEMPERATURE RANGE	PACKAGE
ft2820P	-40°C to +85°C	TSSOP-20L

## ABSOLUTE MAXIMUM RATINGS (Note 1)

PARAMETER	VALUE
Supply Voltage, VDD (AVDD, CVDD)	-0.3V to 5.5V
PVOUT, PVDD, CP1, CP2	-0.3V to 6.5V
All Other Pins	-0.3V to VDD+0.3V
Continuous Total Power Dissipation	Internally Limited
ESD Ratings - Human Body Model (HBM)	2000V
Operating Junction Temperature	-40°C to +150°C
Maximum Soldering Temperature (@10 sec duration)	260°C
Storage Temperature	-45°C to +150°C

Note 1: Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## POWER DISSIPATION RATINGS (Note 2, 3)

PACKAGE	TA ≤ +25°C	TA = +70°C	TA = +85°C	Θ JA
TSSOP-20L	4.8W	3.1W	2.6W	26°C/W

Note 2: The thermal pad of the package must be directly soldered onto a grounded metal island (as a thermal sink) on the system board.

Note 3: The power dissipation ratings are for a two-side, two-plane printed circuit board (PCB).

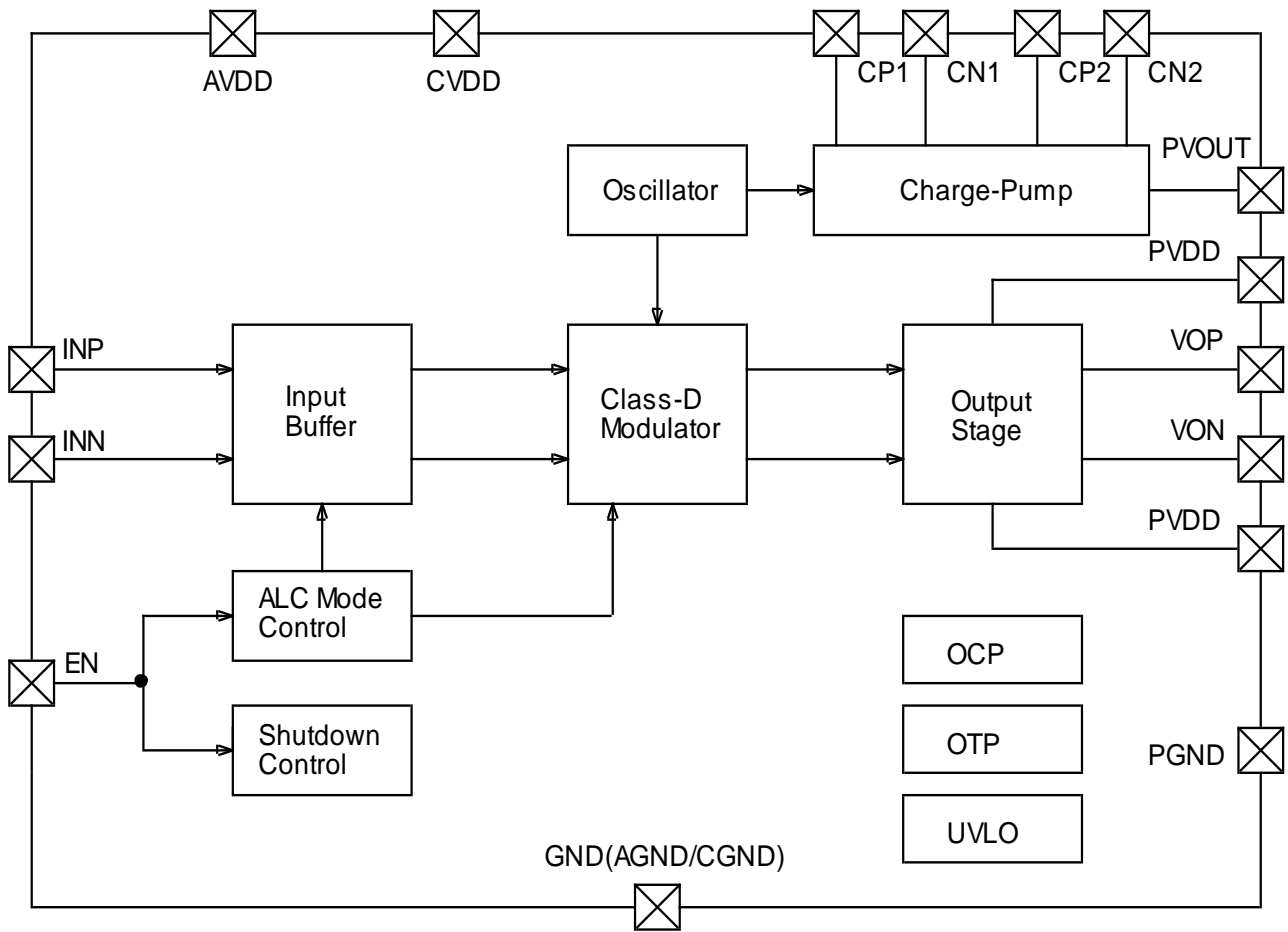
## RECOMMENDED OPERATING CONDITIONS

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Supply Voltage, VDD	AVDD, CVDD	3.0		5.5	V
Operating Free-Air Temperature, TA		-40		85	°C
Minimum Load Resistance, RLOAD		3.2			Ω

## IMPORTANT APPLICATION NOTES

1. The ft2820 is a high performance Class-G audio amplifier with an exposed thermal pad underneath the device. The thermal pad must be directly soldered onto a grounded metal island as a thermal sink for proper power dissipation. Failure to do so may result in the device entering into thermal overload protection.
2. The ft2820 requires adequate power supply decoupling to ensure its optimum operation such as high output power, high efficiency, low THD+N, and low EMI emission. Place respective decoupling capacitors as individually close to the device's AVDD, CVDD, and PVDD pins as possible.
3. It is strongly recommended to employ a ground plane for ft2820 on the system board. Also, place a small decoupling resistor between AVDD and CVDD to prevent high frequency Class-G transient spikes from interfering with the on-chip linear amplifiers.
4. Use a simple ferrite bead filter for further EMI suppression. Choose a ferrite bead with a rated current no less than 2A or greater for applications with a load resistance less than 6Ω. Also, place the respective ferrite bead filters as close to VOP and VON pins as possible.

**FUNCTIONAL BLOCK DIAGRAM**



**Figure 2: ft2820 Simplified Functional Block Diagram**

## ELECTRICAL CHARACTERISTICS

VDD=3.6V, Mode 1, CAVDD=1 $\mu$ F, CCVDD=10 $\mu$ F, CF1=CF2 =2.2 $\mu$ F, COUT=10 $\mu$ F//100uF, f=1kHz, CIN=470nF, RL=4 $\Omega$ +33 $\mu$ H, TA=25°C, unless otherwise specified.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VDD	Supply Voltage	AVDD, CVDD	3.0		5.5	V
VUVLOUP	Power-Up Threshold Voltage	VDD from Low to High		2.2		V
VUVLODN	Power-Off Threshold Voltage	VDD from High to Low		2.0		V
IDD	Supply Quiescent Current Inputs AC-Grounded	EN High, VDD=3.6V		2.7	5	mA
		EN High, VDD=5.0V		3.0	6	mA
ISD	Shutdown Current	VDD = 3.0V to 5.5V, EN Low		0.1	1	$\mu$ A
VIN	EN High Input Voltage		1.2			V
VIL	EN Low Input Voltage				0.4	V
TOTSD	Over-Temperature Threshold			160		°C
THYS	Over-Temperature Hysteresis			20		°C
$\eta$	Power Efficiency	Po=0.5W		82		%
		Po=2.0W		72		%
<b>CHARGE PUMP</b>						
PVOUT	Charge Pump Output Voltage	IPVDD=100mA	5.7	6.0	6.3	V
IOUT	Max. Output Current	VDD=4.2V			1.0	A
TPRECH	Pre-charge time	COUT=10 $\mu$ F//100uF		3		ms
TSS	Soft-start Time	Vin from 0.1VRMS to 0.3VRMS		500		$\mu$ s
fPUMP	Charge Pump Frequency			1		MHz
<b>CLASS-G AMPLIFIER</b>						
PO, MAX	Maximum Output Power Load=8 $\Omega$ +33 $\mu$ H (Mode 3, ALC Off)	THD+N=10%, VDD=4.2V		2.6		W
		THD+N=10%, VDD=3.6V		2.4		
		THD+N=1%, VDD=4.2V		2.1		
		THD+N=1%, VDD=3.6V		2.0		
	Maximum Output Power Load=4 $\Omega$ +33 $\mu$ H (Mode 3, ALC Off)	THD+N=10%, VDD=4.2V		4.0		
		THD+N=10%, VDD=3.6V		3.5		
		THD+N=1%, VDD=4.2V		3.4		
		THD+N=1%, VDD=3.6V		3.0		
PO, ALC	Constant Output Power Load=8 $\Omega$ +33 $\mu$ H (Mode 1 & 2, ALC On)	Vin=300mVRMS, VDD=4.2V		2.0		W
		Vin=300mVRMS, VDD=3.6V		1.9		
	Constant Output Power Load=4 $\Omega$ +33 $\mu$ H (Mode 1 & 2, ALC On)	Vin=300mVRMS, VDD=4.2V		3.3		
		Vin=300mVRMS, VDD=3.6V		2.9		
AV	Overall Voltage Gain	Mode 1 (ALC On)		27.6		dB
		Mode 2 (ALC On)		24.1		
		Mode 3 (ALC Off)		24.1		

## ELECTRICAL CHARACTERISTICS (Cont'd)

VDD=3.6V, Mode 1, CAVDD=1μF, CcVDD=10μF, CF1=CF2 =2.2μF, COUT=10μF//100uF, f=1kHz, CIN=470nF, RL=4Ω+33μH, TA=25°C, unless otherwise specified.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ZIN	Input Impedance @ INP, INN			24		KΩ
ZO	Output Impedance in Shutdown	EN Low		2		KΩ
THD+N	Total Harmonic Distortion + Noise Load=4Ω+33μH (Mode 3, ALC Off)	PO=1.0W		0.05		%
		PO=2.0W		0.06		
	Total Harmonic Distortion + Noise Load=4Ω+33μH, Vin=0.3mVRMS (Mode 1 & 2, ALC On)	VDD=3.6V, PO=2.9W		0.4		%
		VDD=4.2V, PO=3.3W		0.5		
VOS	Output Offset Voltage	Inputs AC-Grounded, No Load		±5		mV
VN	Output Voltage Noise	f=20Hz ~ 20kHz Inputs AC-Grounded, AV=27.6dB		185		μVRMS
PSRR	Power Supply Rejection Ratio	200mVPP Ripple, f=217Hz		75		dB
		200mVPP Ripple, f=1kHz		70		
CMRR	Common Mode Rejection Ratio			70		dB
SNR	Signal-To-Noise Ratio			85		dB
fPWM	PWM Carrier Frequency	VDD=3.6V		1		MHz
TSTUP	Startup Time	VDD=3.6V		32		ms
ILIMIT	Over-Current Limit	VDD=4V, Charge Pump De-biased		2.0		A
THICCUP	Over-Current Recovery Time			200		ms
ALC						
AMAX	Maximum ALC Attenuation			10.5		dB
TATT	ALC Attack Time			32		ms
TREL	ALC Release Time			2.0		s
EN CONTROL						
TLO	Time of EN Low		0.5		10	μs
THI	Time of EN High		0.5			μs
TRST	Time for Mode Reset, Active Low		50		500	μs
TSHDN	Time for Shutdown, Active Low		5			ms

### Note:

- (1) A 33μH inductor was placed in series with the load resistor to emulate a small speaker for efficiency measurements.
- (2) The 33kHz lowpass filter is required even if the analyzer has an internal lowpass filter. An RC lowpass filter (100Ω, 47nF) is used on each output for the data sheet graphs.

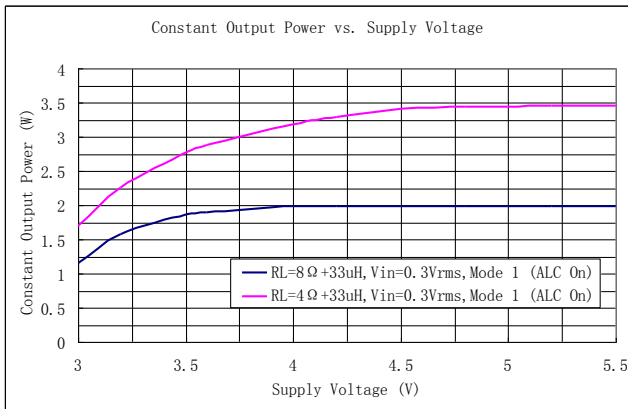
## TYPICAL PERFORMANCE CHARACTERISTICS

### List of Performance Characteristics

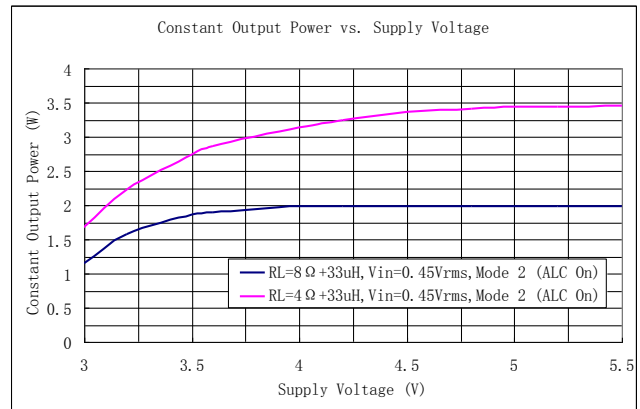
$C_{F1}=C_{F2}=2.2\mu\text{F}$ ,  $C_{OUT}=10\mu\text{F}/100\mu\text{F}$ ,  $C_{AVDD}=1\mu\text{F}$ ,  $C_{CVDD}=10\mu\text{F}$ ,  $C_{IN}=470\text{nF}$ ,  $f=1\text{kHz}$ ,  $T_A=25^\circ\text{C}$ , unless otherwise specified.

DESCRIPTION	CONDITIONS	FIGURE
Constant Output Power vs. Supply Voltage	$R_L=8\Omega+33\mu\text{H}/4\Omega+33\mu\text{H}$ , Mode 1 (ALC On)	3
	$R_L=8\Omega+33\mu\text{H}/4\Omega+33\mu\text{H}$ , Mode 2 (ALC On)	4
Maximum Output Power vs. Supply Voltage	$R_L=8\Omega+33\mu\text{H}$ , THD+N=1%, 10%, Mode 3 (ALC Off)	5
	$R_L=4\Omega+33\mu\text{H}$ , THD+N=1%, 10%, Mode 3 (ALC Off)	6
Output Power vs. Input Voltage	VDD=3.6V, $R_L=8\Omega+33\mu\text{H}$ , Mode 1 & 2	7
	VDD=3.6V, $R_L=8\Omega+33\mu\text{H}$ , Mode 2 & 3	8
	VDD=4.2V, $R_L=8\Omega+33\mu\text{H}$ , Mode 1 & 2	9
	VDD=4.2V, $R_L=8\Omega+33\mu\text{H}$ , Mode 2 & 3	10
	VDD=3.6V, $R_L=4\Omega+33\mu\text{H}$ , Mode 1 & 2	11
	VDD=3.6V, $R_L=4\Omega+33\mu\text{H}$ , Mode 2 & 3	12
	VDD=4.2V, $R_L=4\Omega+33\mu\text{H}$ , Mode 1 & 2	13
	VDD=4.2V, $R_L=4\Omega+33\mu\text{H}$ , Mode 2 & 3	14
Output Power (on Activation of Charge Pump) vs. Supply Voltage	$R_L=8\Omega+33\mu\text{H}$ & $4\Omega+33\mu\text{H}$ , Mode 1 (ALC On)	15
	$R_L=8\Omega+33\mu\text{H}$ & $4\Omega+33\mu\text{H}$ , Mode 3 (ALC Off)	16
Power Dissipation vs. Output Power	$R_L=8\Omega+33\mu\text{H}$ , Mode 1, VDD=3.6V, 4.2V	17
	$R_L=4\Omega+33\mu\text{H}$ , Mode 1, VDD=3.6V, 4.2V	18
Efficiency vs. Output Power	$R_L=8\Omega+33\mu\text{H}$ , Mode 1, VDD=3.6V, 4.2V	19
	$R_L=4\Omega+33\mu\text{H}$ , Mode 1, VDD=3.6V, 4.2V	20
THD+N vs. Output Power	$R_L=8\Omega+33\mu\text{H}$ , Mode 3, VDD=3.6V, 4.2V	21
	$R_L=4\Omega+33\mu\text{H}$ , Mode 3, VDD=3.6V, 4.2V	22
THD+N vs. Input Voltage	$R_L=8\Omega+33\mu\text{H}$ , Mode 1, VDD=3.6V, 4.2V	23
	$R_L=4\Omega+33\mu\text{H}$ , Mode 1, VDD=3.6V, 4.2V	24
	$R_L=8\Omega+33\mu\text{H}$ , Mode 2, VDD=3.6V, 4.2V	25
	$R_L=4\Omega+33\mu\text{H}$ , Mode 2, VDD=3.6V, 4.2V	26
THD+N vs. Input Frequency	VDD=3.6V, $R_L=8\Omega+33\mu\text{H}$ , Mode 1, $P_O=0.25\text{W}$ , 0.5W	27
	VDD=4.2V, $R_L=8\Omega+33\mu\text{H}$ , Mode 1, $P_O=0.25\text{W}$ , 0.5W	28
	VDD=3.6V, $R_L=4\Omega+33\mu\text{H}$ , Mode 1, $P_O=0.5\text{W}$ , 1.0W	29
	VDD=4.2V, $R_L=4\Omega+33\mu\text{H}$ , Mode 1, $P_O=0.5\text{W}$ , 1.0W	30
PSRR vs. Input Frequency	$R_L=8\Omega+33\mu\text{H}$ , Input AC-Grounded, Mode 1, VDD=3.6V, 4.2V	31
	$R_L=4\Omega+33\mu\text{H}$ , Input AC-Grounded, Mode 1, VDD=3.6V, 4.2V	32
Quiescent Current vs. Supply Voltage	Input AC-Grounded, No Load, Mode 1	33
ALC Attack Time	VDD=4.2V, $V_{in}=0.14\text{VRMS}$ to $0.44\text{VRMS}$ , $R_L=4\Omega+33\mu\text{H}$ , Mode 1	34
ALC Release Time	VDD=4.2V, $V_{in}=0.44\text{VRMS}$ to $0.14\text{VRMS}$ , $R_L=4\Omega+33\mu\text{H}$ , Mode 1	35
Charge Pump Mode Transition Waveforms	VDD=4.2V, $V_{in}=50\text{mVRMS}$ ~ $100\text{mVRMS}$ , $R_L=4\Omega+33\mu\text{H}$ , Mode 1	36
(VOP-VON) Startup Waveforms	VDD=4.2V, $R_L=4\Omega+33\mu\text{H}$ , Mode 1	37
(VOP-VON) Shutdown Waveforms	VDD=4.2V, $R_L=4\Omega+33\mu\text{H}$ , Mode 1	38

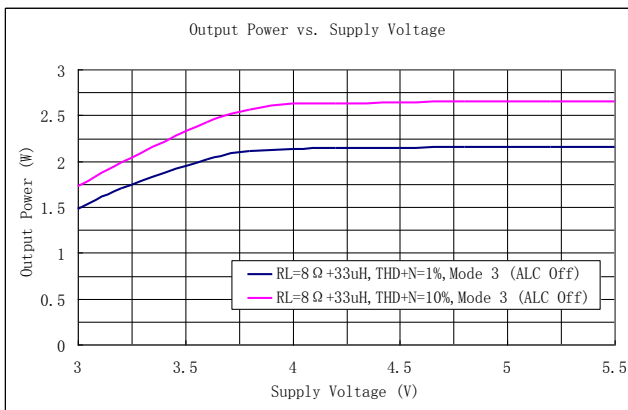
**TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)**



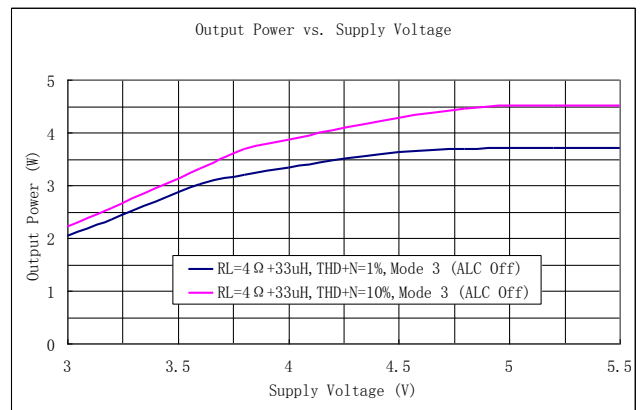
**Figure 3: Constant Output Power vs. Supply Voltage**



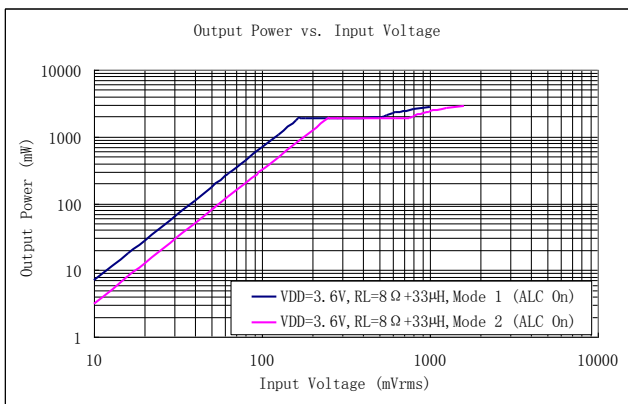
**Figure 4: Constant Output Power vs. Supply Voltage**



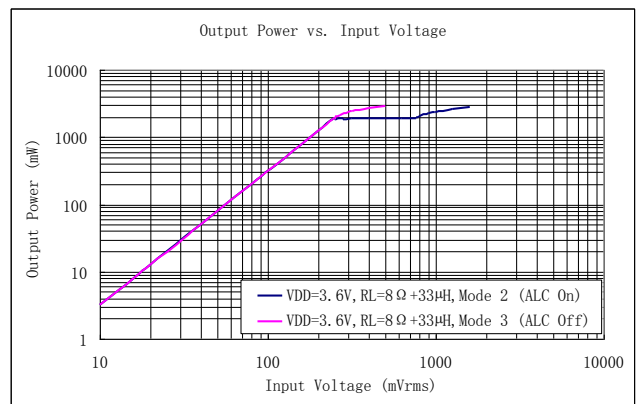
**Figure 5: Output Power vs. Supply Voltage**



**Figure 6: Output Power vs. Supply Voltage**



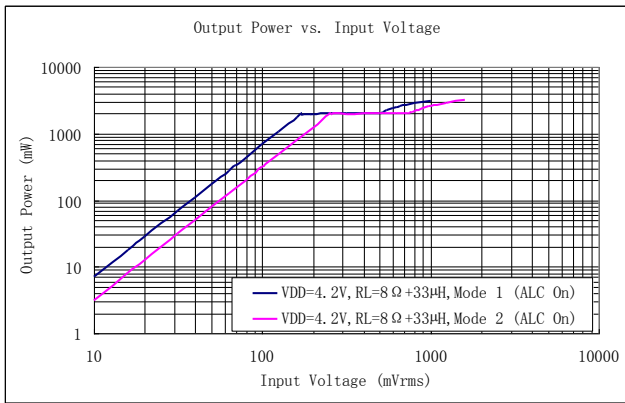
**Figure 7: Output Power vs. Input Voltage**



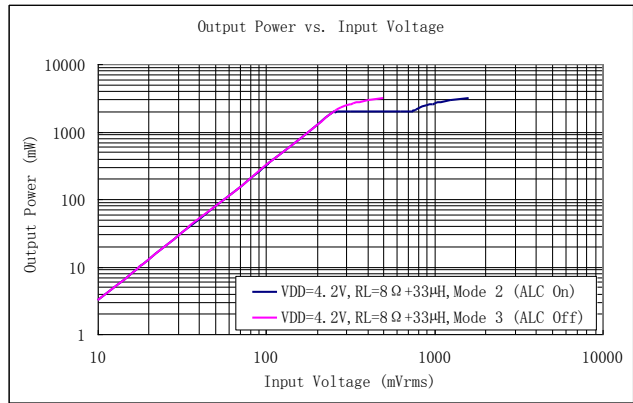
**Figure 8: Output Power vs. Input Voltage**



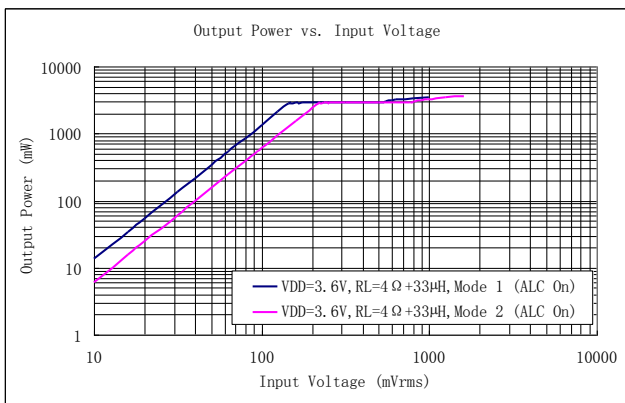
**TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)**



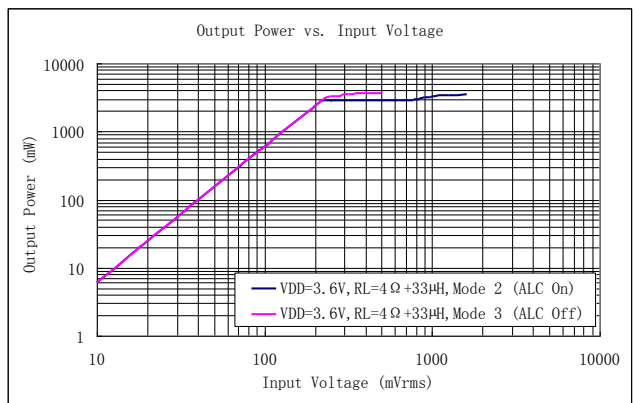
**Figure 9: Output Power vs. Input Voltage**



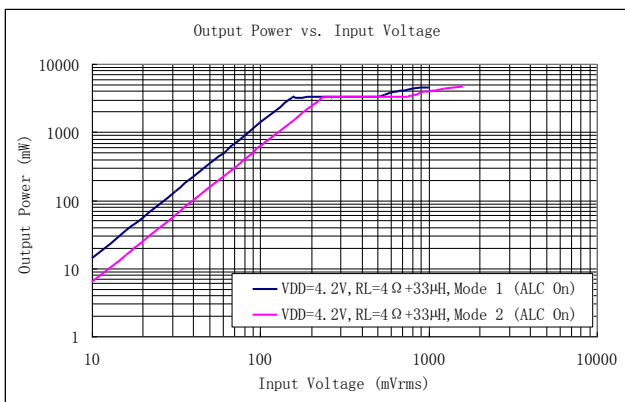
**Figure 10: Output Power vs. Input Voltage**



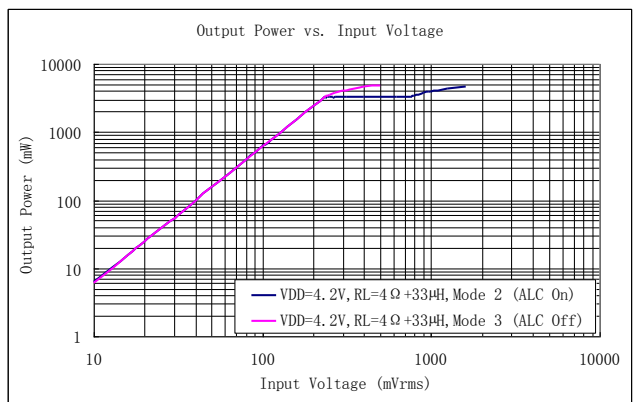
**Figure 11: Output Power vs. Input Voltage**



**Figure 12: Output Power vs. Input Voltage**

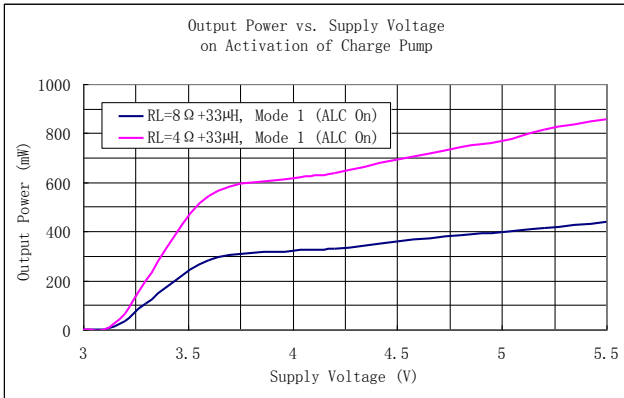


**Figure 13: Output Power vs. Input Voltage**

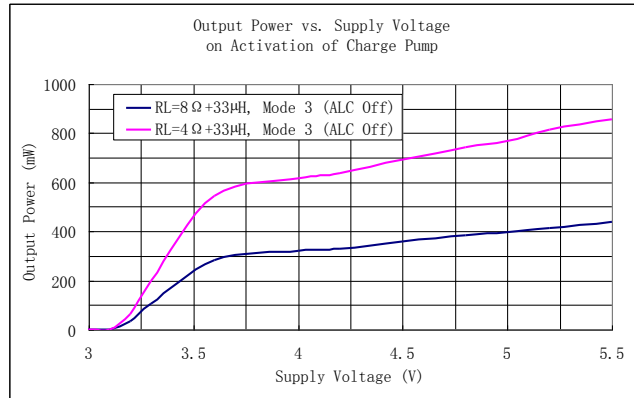


**Figure 14: Output Power vs. Input Voltage**

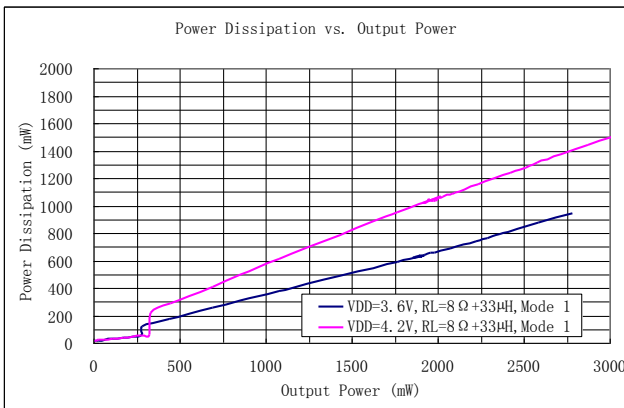
**TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)**



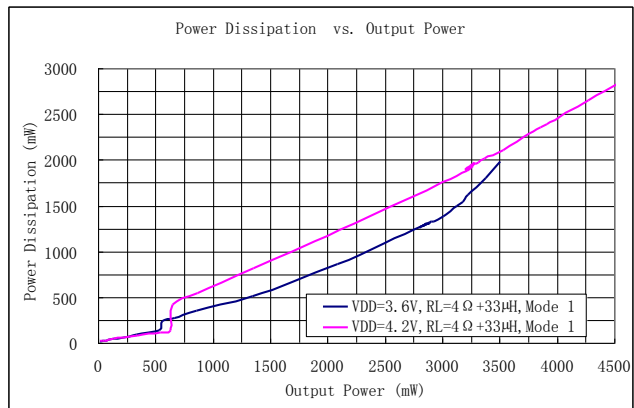
**Figure 15: Output Power (on Activation of Charge Pump) vs. Supply Voltage**



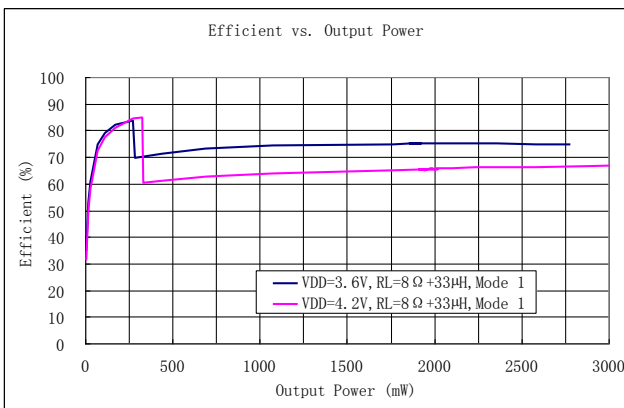
**Figure 16: Output Power (on Activation of Charge Pump) vs. Supply Voltage**



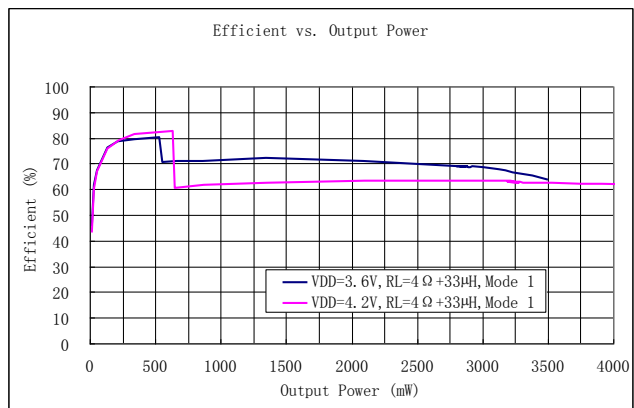
**Figure 17: Power Dissipation vs. Output Power**



**Figure 18: Power Dissipation vs. Output Power**

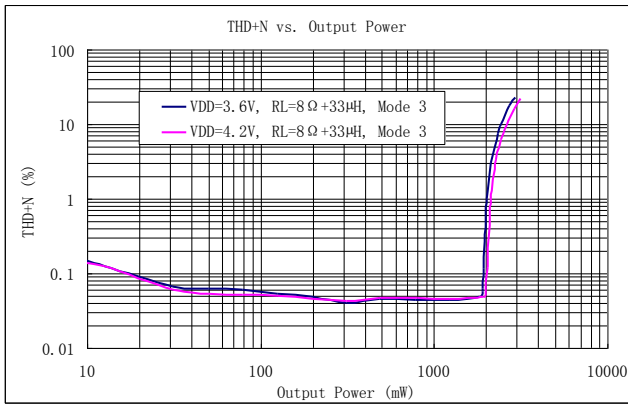


**Figure 19: Efficiency vs. Output Power**

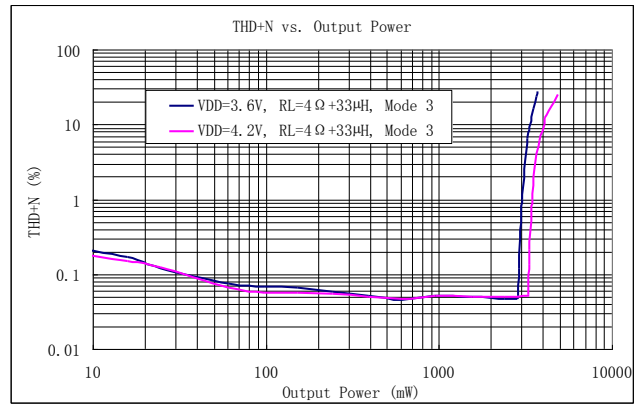


**Figure 20: Efficiency vs. Output Power**

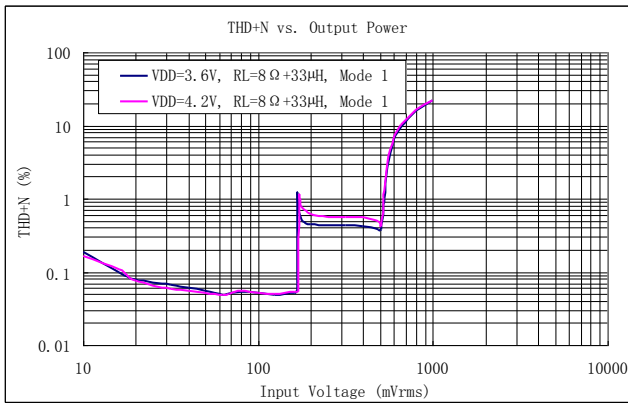
**TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)**



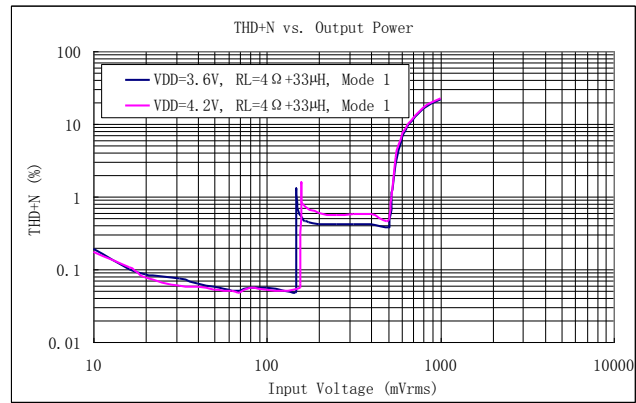
**Figure 21: THD+N vs. Output Power**



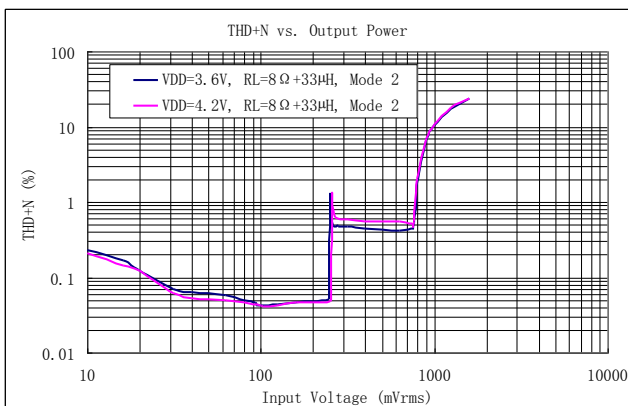
**Figure 22: THD+N vs. Output Power**



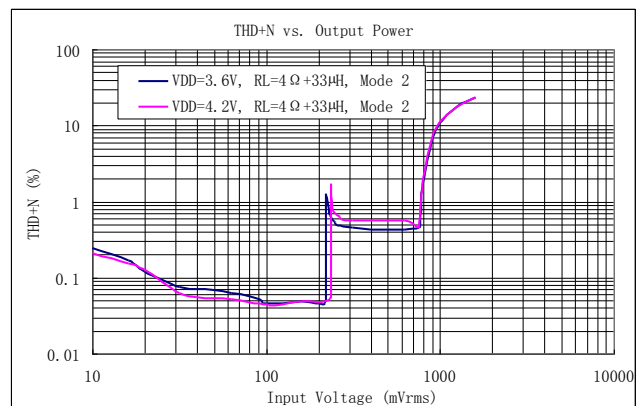
**Figure 23: THD+N vs. Input Voltage**



**Figure 24: THD+N vs. Input Voltage**

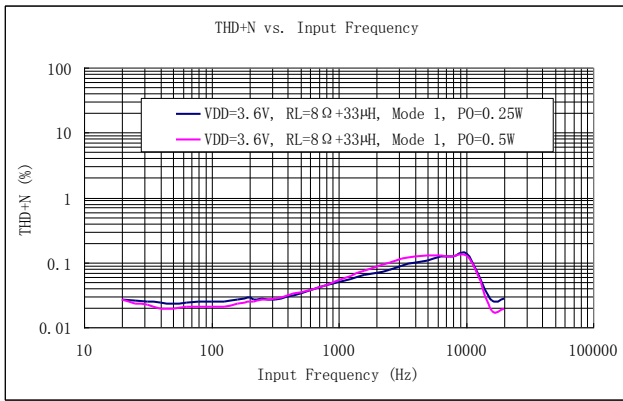


**Figure 25: THD+N vs. Input Voltage**

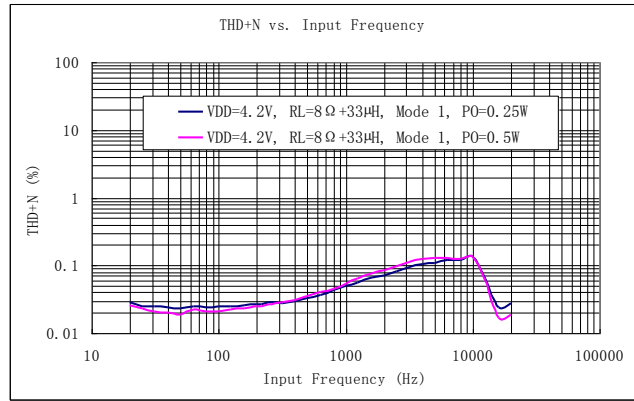


**Figure 26: THD+N vs. Input Voltage**

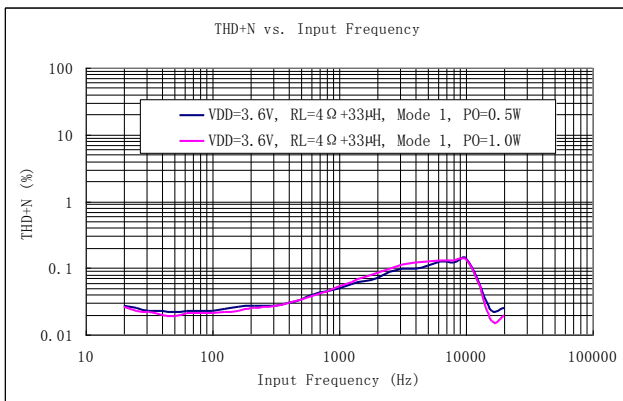
**TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)**



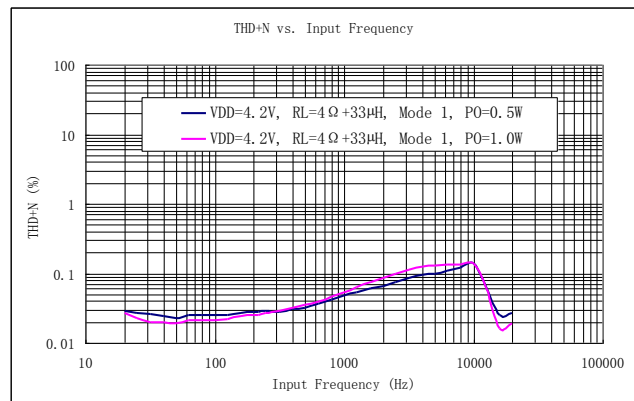
**Figure 27: THD+N vs. Input Frequency**



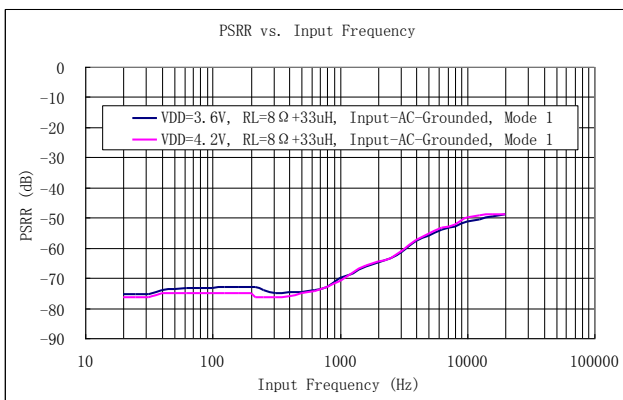
**Figure 28: THD+N vs. Input Frequency**



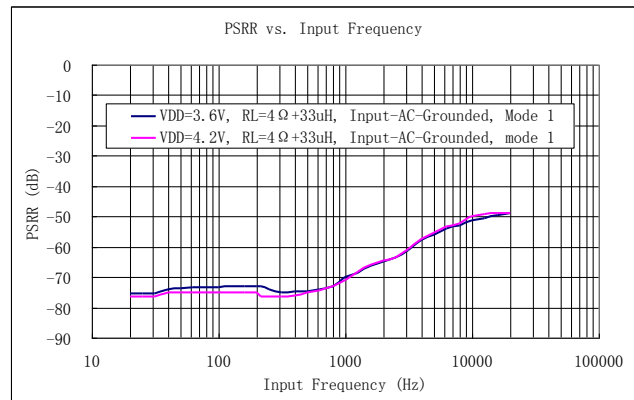
**Figure 29: THD+N vs. Input Frequency**



**Figure 30: THD+N vs. Input Frequency**



**Figure 31: PSRR vs. Input Frequency**



**Figure 32: PSRR vs. Input Frequency**

TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

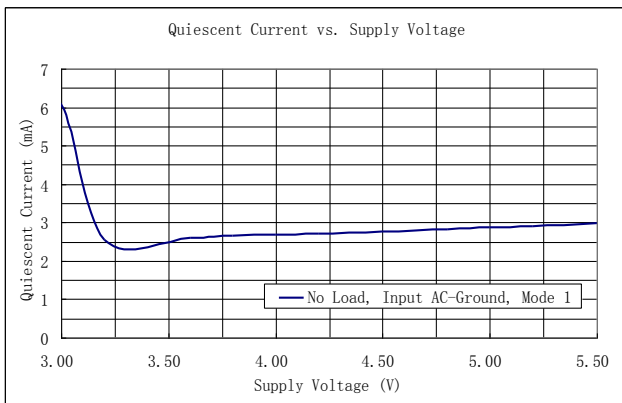


Figure 33: Quiescent Current vs. Supply Voltage

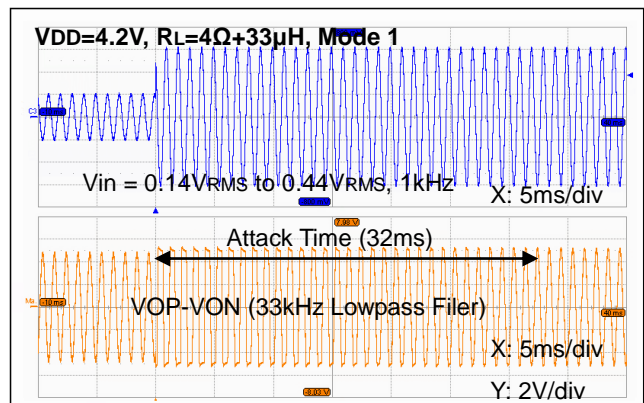


Figure 34: ALC Attack Time

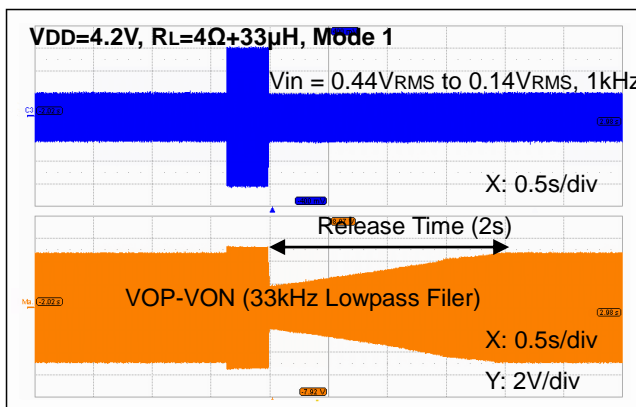


Figure 35: ALC Release Time

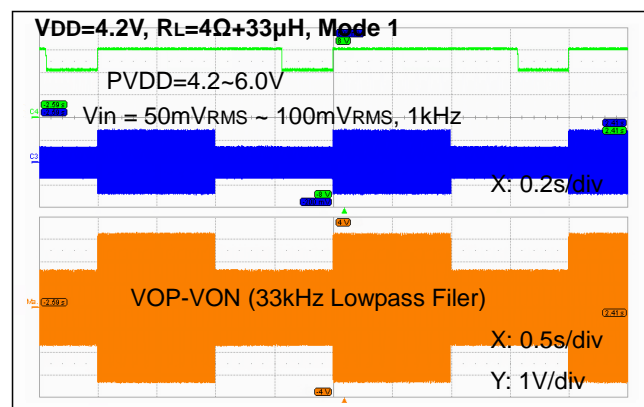


Figure 36: Charge Pump Mode Transition Waveforms

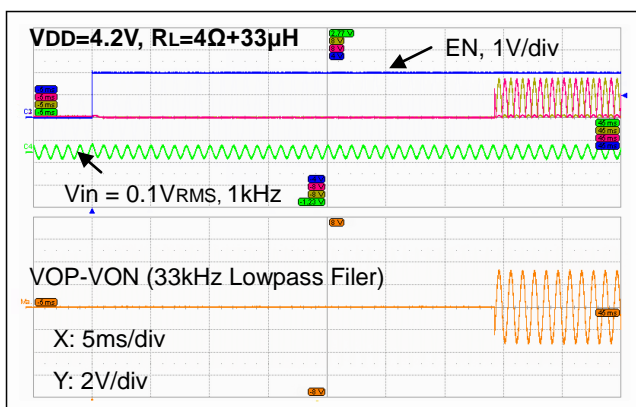


Figure 37: (VOP-VON) Startup Waveforms

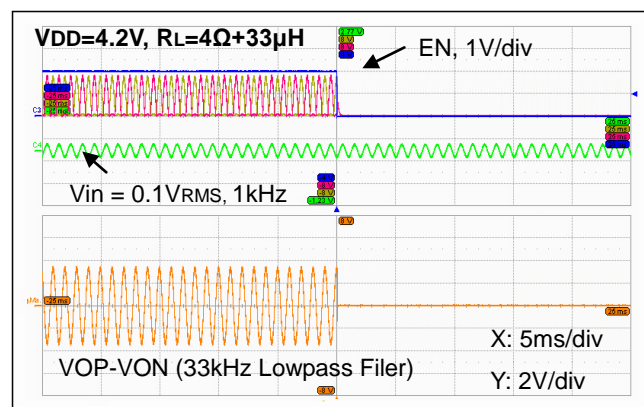


Figure 38: (VOP-VON) Shutdown Waveforms

## APPLICATION INFORMATION

The ft2820 is a 4W boosted Class-G audio power amplifier based upon a proprietary **Dual-Pump™** topology with automatic level control (ALC). It operates from 3V to 5.5V supply. When operating with a 4.2V supply voltage, it is capable of driving a 4Ω speaker load at a continuous average output of 4W with 10% THD+N. Its high efficiency, up to 82%, helps extend battery life for portable device applications.

In ft2820, the power supply rail of the amplifier output stage is internally boosted and regulated at 6V by an integrated adaptive charge pump based upon the **Dual-Pump™** topology, thus allowing for a much louder audio output than a stand-alone one directly connected to the battery. It makes ft2820 an ideal audio solution for portable devices, which are powered by a single-cell lithium battery while requiring higher audio loudness.

The ft2820 also features ALC on the output signals, which detects the output clipping caused by the over-level input signal and automatically adjusts the dynamic range of the output signals to prevent the distortion of the audio signal. The ALC also eliminates the output clipping due to low battery supply voltage.

As specifically designed for portable device applications, the ft2820 incorporates a shutdown mode to minimize the power consumption by holding the EN pin to ground. It also includes comprehensive protection features against various operating faults such as over-current, short-circuit, over-temperature, and under-voltage for a safe and reliable operation.

## ADAPTIVE CHARGE PUMP

To allow for a much louder audio output, a charge pump circuit is employed to boost PVDD, the power rail for the amplifier output stage. Whenever the audio inputs are larger than a prescribed level for an extended period of time, the charge pump will be activated to boost and regulate PVOUT at 6V. In this case, the charge pump operates in the regulation mode. For a proper operation, the boosted voltage PVOUT generated by the charge pump must be externally shorted to PVDD via a sufficiently wide metal trace on the system board.

On the other hand, when the audio inputs are less than a prescribed level for an extended period of time, the charge pump will be de-biased and forced into the standby mode. In the standby mode, the amplifier output stage is powered directly by VDD, the battery voltage, through an internal power switch. This adaptive nature of the charge pump circuit can greatly improve the power efficiency of ft2820 when playing audio and thus extends battery life.

## DUAL-PUMP™ TECHNOLOGY

In order to maximize the output power, the ft2820 employs a proprietary **Dual-Pump™** topology for the internal charge pump using two flying capacitors to boost the supply voltage to a higher value at 6V. To limit the inrush current to an acceptable value when the supply voltage is first applied to the device, the charge pump incorporates soft-start function. Furthermore, when a short-circuit condition at the boosted voltage is detected, the ft2820 limits the charging current to about 100mA for a safe operation.

Compared with a conventional charge pump topology using a single flying capacitor, the output current capability of the **Dual-Pump™** can be largely enhanced and the output voltage ripples minimized. In this manner, the performance of the Class-G amplifier can be significantly improved, particularly for the speakers whose impedance is less than 6Ω. With the **Dual-Pump™** topology, the ft2820 can deliver up to 4W into a 4Ω speaker load with 10% THD+N when powered by a single-cell lithium battery.

**Selection of Charge Pump Flying Capacitors (CF1 & CF2)**

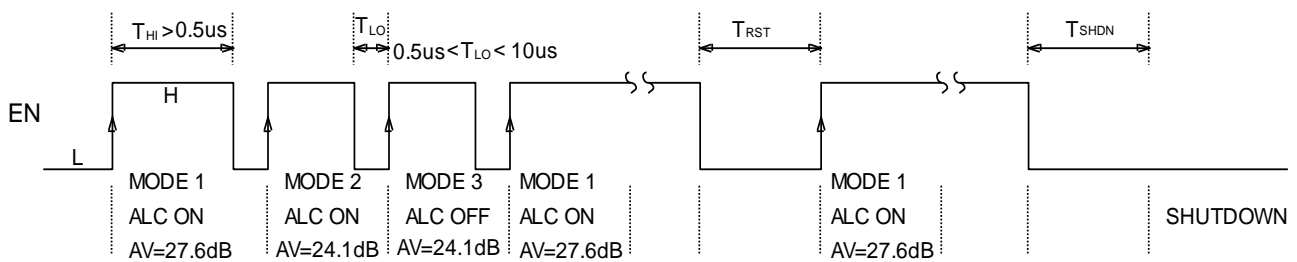
A nominal value of 2.2µF is recommended for the flying capacitors (CF1 and CF2) of the charge pump, but other values can be used. A low equivalent-series-resistance (ESR) ceramic capacitor, such as X7R or X5R, is recommended.

**Selection of Charge Pump Output Capacitor (COUT)**

For best performance, a 10µF low ESR ceramic capacitor in parallel with a 100µF tantalum or electrolytic capacitor is recommended for the output capacitor (COUT) of the charge pump, but other values can be used.

**OPERATING MODE CONTROL AND GAIN SETTING**

To support for a wide range of applications, the ft2820 incorporates one-wire pulse control to configure the operating mode and the voltage gain. By applying a string of pulses to the EN pin, users can enable (Constant Output Power mode) or disable (Maximum Output Power mode) the ALC function as well as set the voltage gain. The operating mode is advanced and updated on each low-to-high transition of the pulses applied onto the EN pin. The detailed timing diagram of the one-wire pulse control to select the operating mode is shown in Figure 39.



**Figure 39: Operating Mode Control Diagram**

Three operating modes are configured by the application of a string of pulses onto the EN pin. After an initial application of the power supply, the first low-to-high transition at the EN pin will set the device into Mode 1, where the voltage gain is set at 27.6dB and the ALC function enabled. On the next low-to-high transition, the device advances into Mode 2, where the voltage gain is set at 24.1dB and the ALC function remains enabled. Finally, on the third low-to-high transition, the device advances into Mode 3, where the ALC function is disabled and the voltage gain remains at 24.1dB. The operating modes will be cycled and repeated in the same manner as described above for consecutive pulses applied.

Note that each individual pulse must be longer than a minimum of 0.5µs to be recognized. Any pulses shorter than 0.5µs may be ignored. The state of the mode operation can be reset back to Mode 1 by holding the EN pin low more than 50µs but less than 500µs, regardless of the state it is currently operating. Whenever the EN pin held low for more than 5ms, the device enters into the shutdown mode, where all the internal circuitry is de-biased. Once the device is forced into shutdown mode, one or multiple pulses are required for the ft2820 to return to the desired mode of operation.

Mode	# of Pulses	Voltage Gain	ALC Function
Mode 1	1	27.6dB (24X)	Enable
Mode 2	2	24.1dB (16X)	Enable
Mode 3	3	24.1dB (16X)	Disable

**Table 1: Mode of Operation**

**Operating Mode Reset**

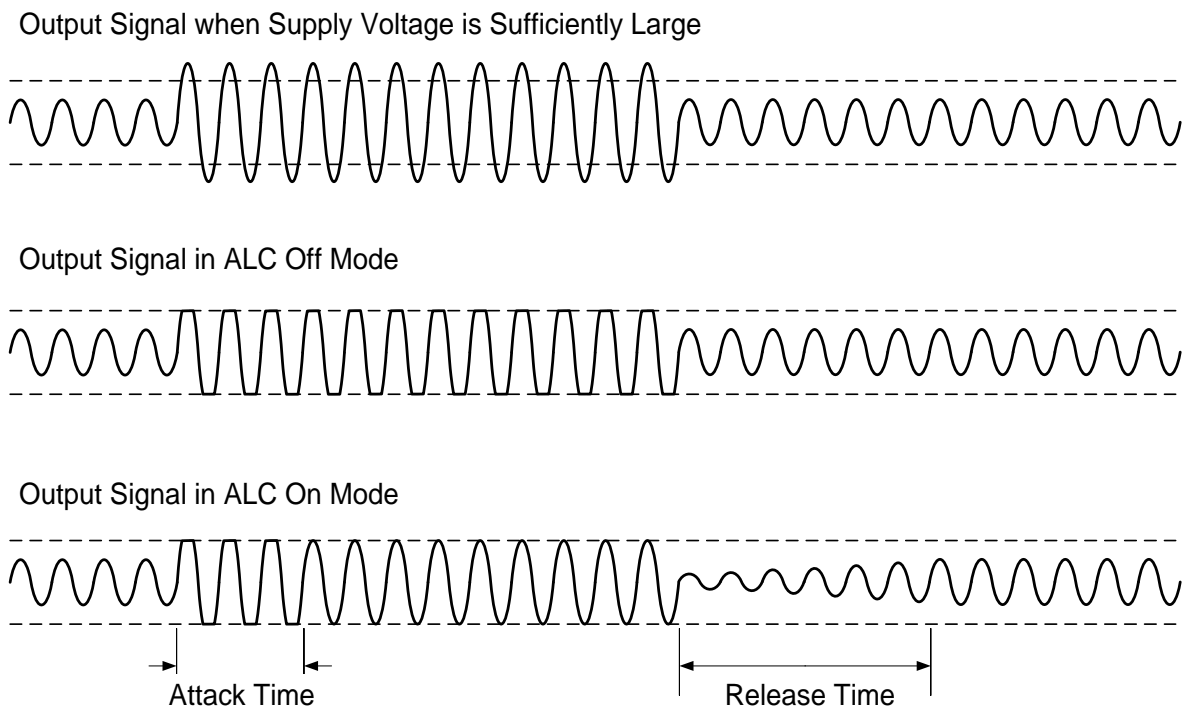
The state of the mode operation can be reset back to the default mode, Mode 1 (Av=27.6dB, ALC On) by holding the EN pin low for more than 50µs but less than 500µs, regardless of the state it is currently operating.

**Shutdown Mode**

When the EN pin is held low for 5ms (typical) or longer, the ft2820 will be forced into the shutdown mode. During the shutdown mode, the supply current will be significantly reduced to less than 1µA.

**AUTOMATIC LEVEL CONTROL (ALC)**

The automatic level control is to maintain the output signal level for a maximum output swing without distortion when an excessive input that may cause output clipping is applied. With the ALC function, the ft2820 lowers the gain of the amplifier to an appropriate value such that the clipping at the output is avoided. It also eliminates the clipping of the output signal due to the decrease of the power-supply voltage.



**Figure 40: Automatic Level Control Function Diagram**



The attack time is defined as the time interval required for the gain to fall to its steady-state gain less 3dB approximately, presumed that a sufficiently large input signal is applied. The release time is the time interval required for the amplifier to exit out of the present mode of operation. See Table 2.

Mode	Attack Time (ms)	Release Time (s)
Mode 1 & 2 (ALC On)	32	2.0

**Table 2: Attack Time & Release Time**

### Click-and-Pop Suppression

The ft2820 audio power amplifier features comprehensive click-and-pop suppression. During startup, the click-and-pop suppression circuitry reduces any audible transients internal to the device. When entering into shutdown, the differential audio outputs are pulled to ground through their individual internal resistors (2K $\Omega$ ) simultaneously.

### PSRR Enhancement

Without a dedicated pin for the common-mode voltage bias and an external holding capacitor onto the pin, the ft2820 achieves a high PSRR, 75dB at 217Hz, thanks to a proprietary design technique.

## PROTECTION MODES

The ft2820 incorporates various protection functions against possible operating faults for a safe operation. It includes Under-voltage Lockout (UVLO), Over-Current Protection (OCP), and Over-Temperature Shutdown (OTSD).

### Under-Voltage Lockout (UVLO)

The ft2820 incorporates a circuitry to detect a low supply voltage for a safe and reliable operation. When the supply voltage is first applied, the ft2820 will remain inactive until the supply voltage exceeds 2.2V ( $V_{UVLU}$ ). When the supply voltage is removed and drops below 2.0V ( $V_{UVLD}$ ), the ft2820 enters into shutdown mode immediately.

### Over-Current Protection (OCP)

During operation, the output of Class-G amplifier constantly monitors for any over-current and/or short-circuit conditions. When a short-circuit condition between two differential outputs, differential output to VDD, PVDD or ground is detected, the output stage of the amplifier is immediately forced into high impedance state. Once the fault condition persists over a prescribed period, the ft2820 then enters into the shutdown mode and remains in this mode for about 200ms. During the shutdown, the power switches of the charge pump are also turned off, and the PVDD is discharged through a resistor to ground.

When the shutdown mode times out, the ft2820 will initiate another startup sequence and then check if the short-circuit condition has been removed. Meanwhile, the charge pump tries to bring PVDD up to the preset voltage again. If the fault condition is still present, the ft2820 will repeat itself for the process of a startup followed by detection, qualification, and shutdown. It is so-called the hiccup mode of operation. Once the fault condition is removed, the ft2820 automatically restores to its normal mode of operation.

### **Over-Temperature Shutdown (OTSD)**

When the die temperature exceeds a preset threshold (160°C), the device enters into the over-temperature shutdown mode, where two differential outputs are pulled to ground through an internal resistor (2KΩ) individually. The device will resume normal operation once the die temperature returns to a lower temperature, which is about 20°C lower than the threshold.

## **CLASS-G AUDIO AMPLIFIER**

The Class-G audio amplifier in the ft2820 operates in much the same way as a traditional Class-D amplifier and similarly offers much higher power efficiency than Class-AB amplifiers. The high efficiency of a Class-G operation is achieved by the switching operation of the output stage of the amplifier. The power loss associated with the output stage is limited to the conduction and switching loss of the power MOSFETs, which are much less than the power loss associated with a linear output stage in Class-AB amplifiers.

### **Fully Differential Amplifier**

The ft2820 includes a fully differential amplifier with differential inputs and outputs. The fully differential amplifier consists of a differential amplifier and a common-mode amplifier. The differential amplifier ensures that the amplifier outputs a differential voltage on the output that is equal to the differential input times the amplifier gain. The common-mode feedback ensures that the common-mode voltage at the output is biased substantially close to an internally-generated voltage reference regardless of the common-mode voltage of the inputs. Although the ft2820 supports for a single-ended input, differential inputs are recommended for the applications, where the environment can be noisy like a wireless handset, in order to ensure maximum SNR.

### **Low-EMI Filterless Output Stage**

Traditional Class-D amplifiers require for the use of external LC filters, or shielding, to meet EN55022B electromagnetic-interference (EMI) regulation standards. The ft2820 applies an edge-rate control circuitry to reduce EMI emission, while maintaining high power efficiency. Above 10MHz, the wideband spectrum looks like noise for EMI purposes.

### **Filterless Design**

Traditional Class D amplifiers require an output filter to recover the audio signal from the amplifier's output. The filter adds cost, increases the solution size of the amplifier, and can decrease efficiency and THD+N performance. The traditional PWM scheme uses large differential output swings (twice of supply voltage peak-to-peak) and causes large ripple currents. Any parasitic resistance in the filter components results in loss of power and lowers the efficiency.

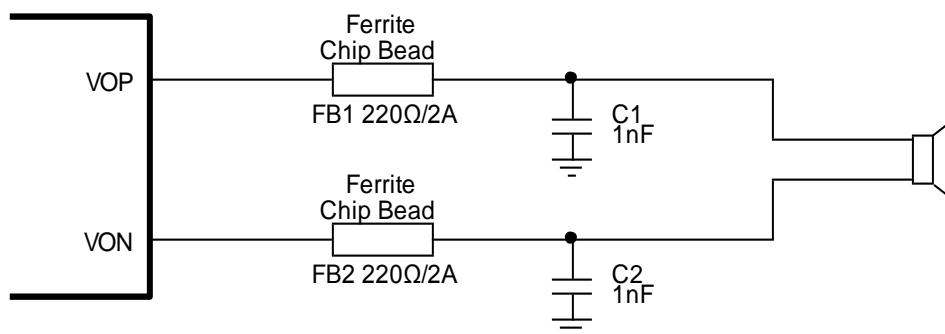
The ft2820 does not require an output filter. The device relies on the inherent inductance of the speaker coil and the natural filtering of both the speaker and the human ear to recover the audio component of the square-wave output. By eliminating the output filter, a smaller, less costly, and more efficient solution can be accomplished.

Because the frequency of the ft2820 output is well beyond the bandwidth of most speakers, voice coil movement due to the square-wave frequency is very small. Although this movement is small, a speaker

not designed to handle the additional power can be damaged. For optimum results, use a speaker with a series inductance greater than 10uH. Typical 8Ω speakers exhibit series inductances in the range from 20uH to 100uH.

**EMI Reduction**

The ft2820 does not require an LC output filter for short connections from the amplifier to the speaker. However, additional EMI suppressions can be made by use of a ferrite bead in conjunction with a capacitor, as shown in Figure 41. Choose a ferrite bead with low DC resistance (DCR) and high impedance (100Ω ~ 220Ω) at high frequencies (>100MHz). The current flowing through the ferrite bead must be also taken into consideration. The effectiveness of ferrites can be greatly aggravated at much lower than the rated current values. Choose a ferrite bead with a rated current value no less than 2A. The capacitor value varies based on the ferrite bead chosen and the actual speaker lead length. Choose a capacitor less than 1nF based on EMI performance



**Figure 41: Ferrite Bead Filter to Reduce EMI**

**Decoupling Capacitor (Cs)**

The ft2820 is a high-performance Class-G audio power amplifier, which requires adequate power supply decoupling to ensure its high efficiency operation with low total harmonic distortion. Sufficient power supply coupling also prevents oscillations for long lead lengths between the amplifier and the speaker.

Place a low equivalent-series-resistance (ESR) ceramic capacitor (X7R or X5R), typically 1μF, as close as possible to the AVDD lead. This choice of capacitor and placement help reject high frequency transients, spikes, or digital hash on the line. Furthermore, placing the decoupling capacitors close to the ft2820 is important for power efficiency, as any parasitic resistance or inductance between the amplifier and the capacitor causes efficiency loss. For best power supply coupling, place an additional 10μF or greater low ESR capacitor close to the CVDD lead. This larger capacitor serves as a charge reservoir for the flying capacitors CF1 or CF2 of the charge pump each time one of the flying capacitors is charged, thus reducing the amount of voltage ripple seen at CVDD. This will help reduce the amount of EMI passed back along the power trace to other circuitry on the system board.

**Input Resistors (Rin)**

To minimize the number of external components required for the application of ft2820, a set of 24KΩ input resistors are integrated internally at INP and INN pins respectively. The internal input resistors also bring other benefits such as fewer variations on PSRR and turn-on pop noise performances since on-chip resistors can match well. Thus, for typical portable device applications, there is no need for additional

input resistors connected to INP or INN pin. However, for applications where additional gain adjustment becomes necessary, a set of external input resistors can be added onto INP and INN pins respectively, as shown in Figure 45. The value of the external input resistors must be included for the calculation of the overall voltage gain (as described in Equation 1) as well as the selection of proper input capacitors (as described in Equation 2). As shown in Equation 1, the external input resistors will attenuate the original overall voltage gain by the ratio of  $R_{INTERNAL} / (R_{IN} + R_{INTERNAL})$ .

$$AV = AV_0 \times [R_{INTERNAL} / (R_{IN} + R_{INTERNAL})] \quad (1)$$

Where  $AV_0 = 24$  (27.6dB) for Mode 1  
 $AV_0 = 16$  (24.1dB) for Mode 2 and 3

### Input Capacitors ( $C_{IN}$ )

DC decoupling capacitors for audio inputs are recommended. The audio input DC decoupling capacitors will remove the DC bias from an incoming analog signal. The input capacitors ( $C_{IN}$ ) and input resistors ( $R_{IN}$  plus  $R_{INTERNAL}$ ) form a highpass filter with the corner frequency,  $f_C$ , as shown in Equation 2.

$$f_C = 1 / [2 \times \pi \times (R_{IN} + R_{INTERNAL}) \times C_{IN}] \quad (2)$$

Where  $R_{INTERNAL} = 24K\Omega$

Choose  $C_{IN}$  such that the  $f_C$  is well below the lowest frequency of interest. Setting  $f_C$  too high affects the low frequency responses of the amplifier. Consider an example where the specification calls for  $AV=28dB$  and a flat frequency response down to 20Hz. In this example,  $R_{IN}=0K\Omega$  and  $C_{IN}$  is calculated to be 0.33 $\mu F$ .

Note that any mismatch in capacitance between two audio inputs will cause a mismatch in the corner frequencies. Severe mismatch may also cause turn-on pop noise, PSRR, CMRR performance. Choose capacitors with a tolerance of  $\pm 5\%$  or better.

Furthermore, the type of the input capacitor is crucial to audio quality. For best audio quality, use capacitors whose dielectrics have low-voltage coefficients, such as tantalum or aluminum electrolytic. Capacitors with high-voltage coefficients, such as ceramics, may result in increased distortion at low frequencies.

## PRINTED CIRCUIT BOARD (PCB) LAYOUT

Supply Decoupling Capacitors – Local high-frequency bypass capacitors,  $C_s$ , should be individually placed as close to the AVDD and CVDD pins as possible. Place a 10 $\mu F$  capacitor close to the CVDD pin and 1 $\mu F$  capacitor close to the AVDD pin. Also, on the system board, place large bulk power supply decoupling capacitors (100 $\mu F$  or greater) on the VDD supplies as close to the ft2820 as possible. These capacitors can be connected to the IC ground pad, GND, directly for good ground connection.

Flying Capacitors – Place the CF1 flying capacitor as close to the CP1 and CN1 pins as possible and the CF2 flying capacitor as close to the CP2 and CN2 pins as possible.

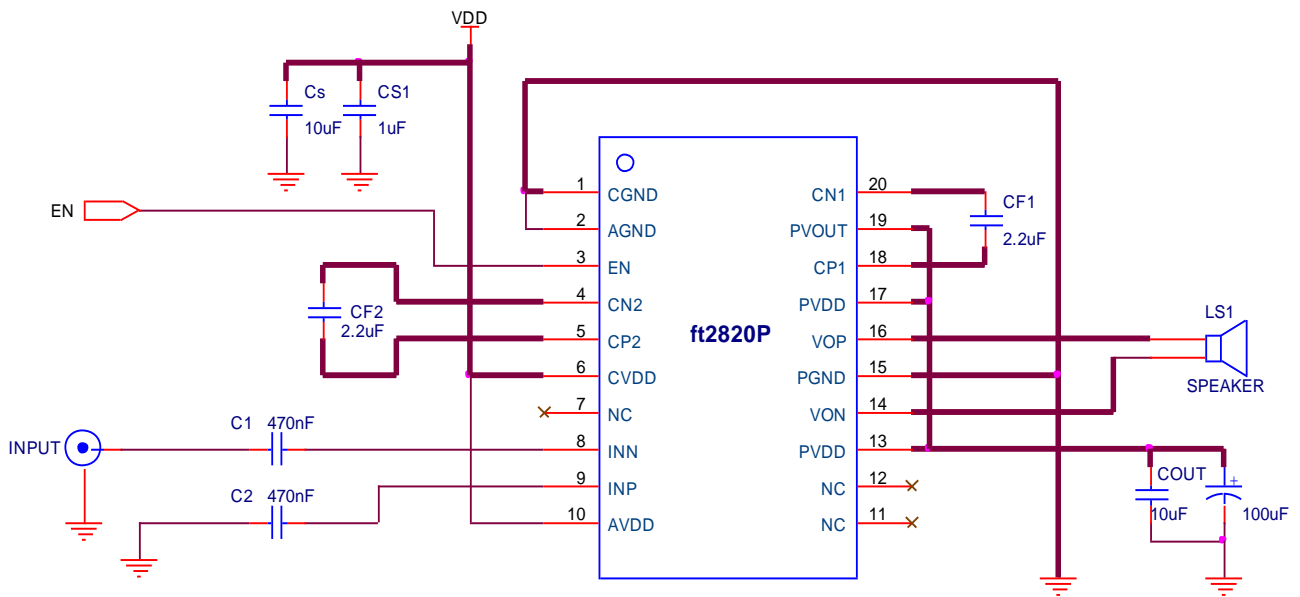
Boosted Voltage Holding Capacitor – The boosted voltage holding capacitor,  $C_{OUT}$ , should be placed as close to the PVDD pins as possible. Also, it is required to short the PVOOUT pin to the PVDD pins directly by a wide and short metal trace on the system board. For high power (greater than 2.4W) applications, it is strongly recommended to place a 100 $\mu F$  tantalum or electrolytic capacitor in parallel with a 10  $\mu F$  ceramic capacitor.

EMI – The ferrite EMI filters should be placed as close to the output terminals as possible for the best EMI performance. Keep the current loop from each of the outputs (VOP and VON) through the ferrite bead, the small filter capacitor, and back to PGND short and in close proximity.

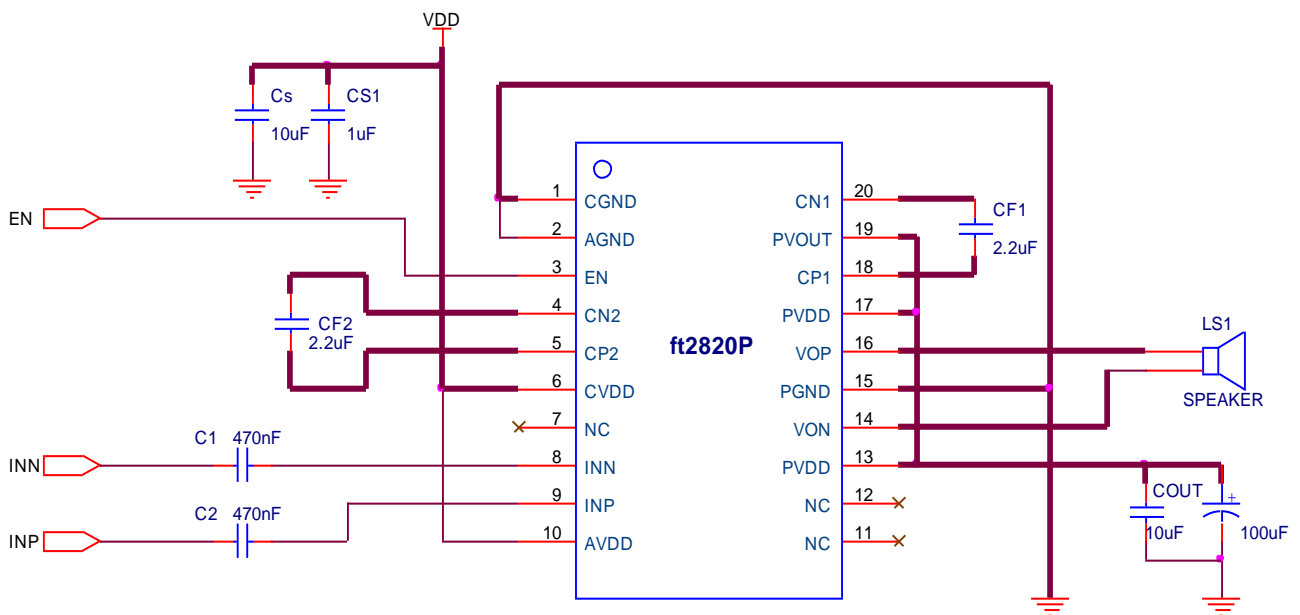
Grounding – It is required to employ a solid metal plane as a central ground connection or star ground for the ft2820. All ground pins should be individually connected to the star ground pad GND with sufficiently wide traces.

Thermal Pad – The thermal pad must be directly soldered onto a grounded metal pad for proper power dissipation to ensure optimal performance and long-term reliability. Place sufficient number of solid VIAs (whose diameter is 0.3mm or less) equally spaced underneath the thermal pad. The VIAs should be connected to a solid copper plane, either on an internal layer or on the bottom layer of the system board. Note that the VIAs must be solid ones, not thermal relief or webbed VIAs.

**TYPICAL APPLICATION CIRCUITS**



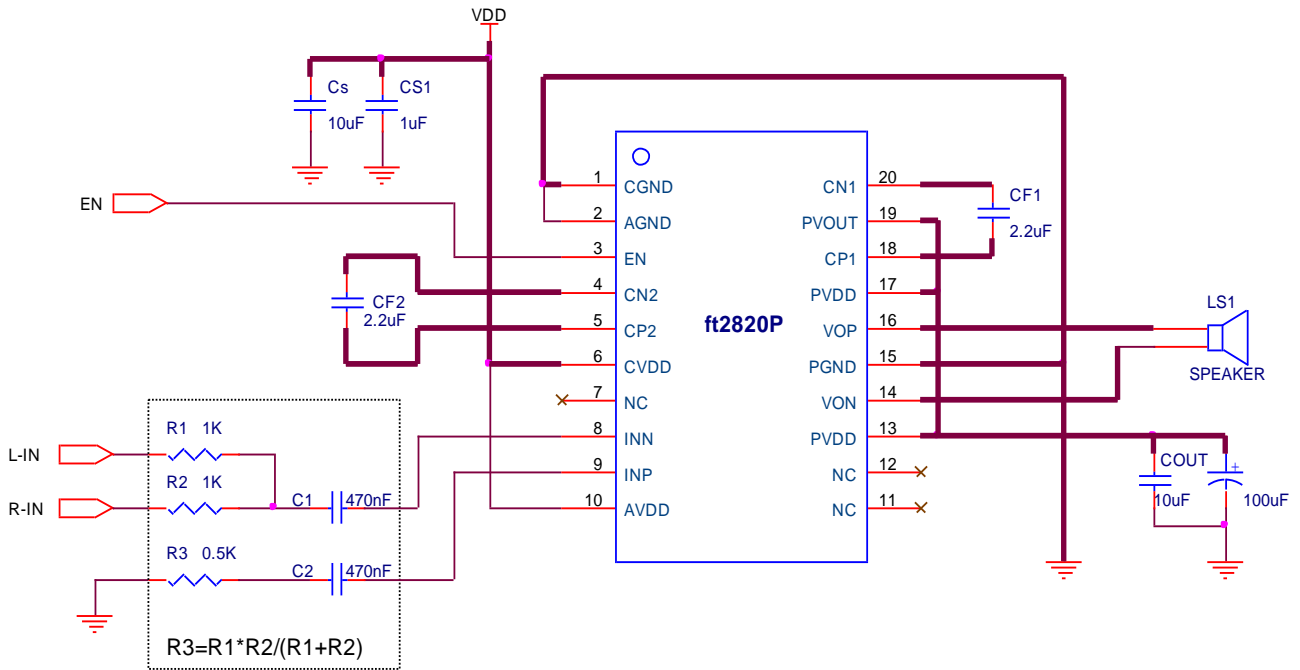
**Figure 42: Single-Ended Audio Input**



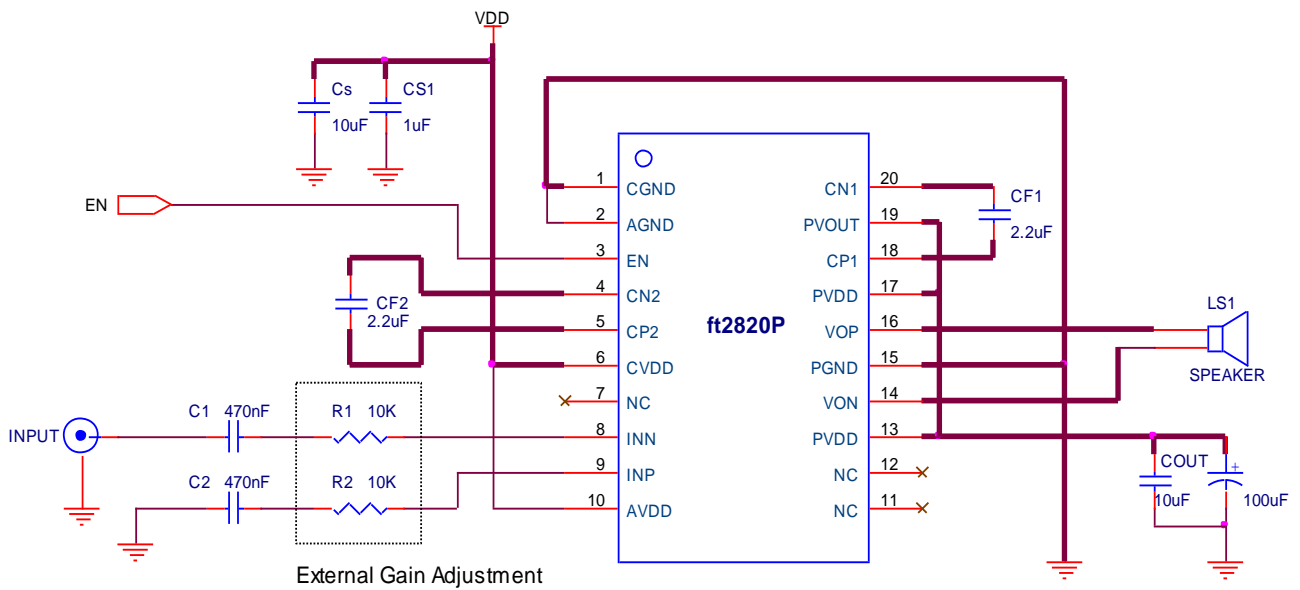
**Figure 43: Differential Audio Inputs**

Note: The bold lines are high current paths and their respective traces are required to be as wide and short as possible on the system board for high power applications.

**TYPICAL APPLICATION CIRCUITS (Cont'd)**



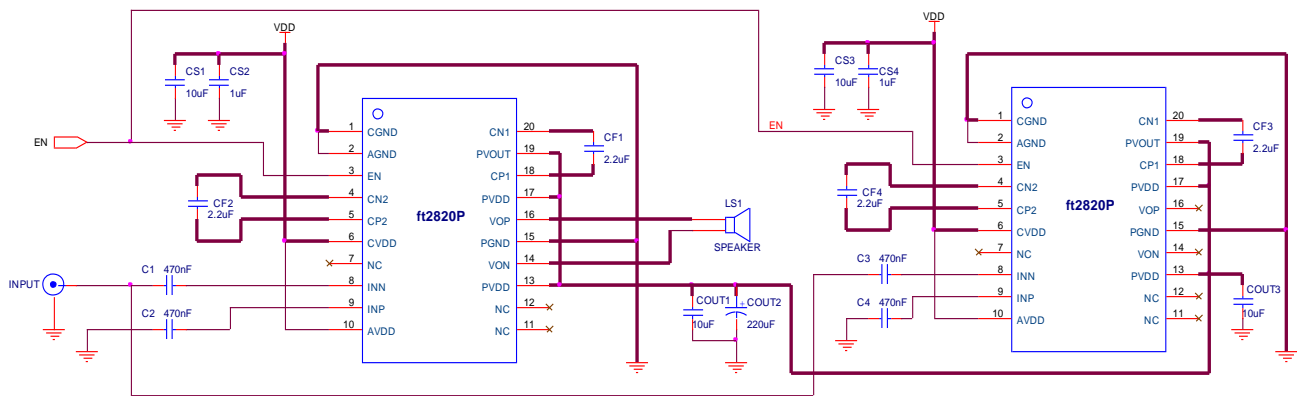
**Figure 44: Dual Channel Audio Inputs**



**Figure 45: Single-Ended Audio Input with External Gain Adjustment**

Note: The bold lines are high current paths and their respective traces are required to be as wide and short as possible on the system board for high power applications.

**TYPICAL APPLICATION CIRCUITS (Cont'd)**



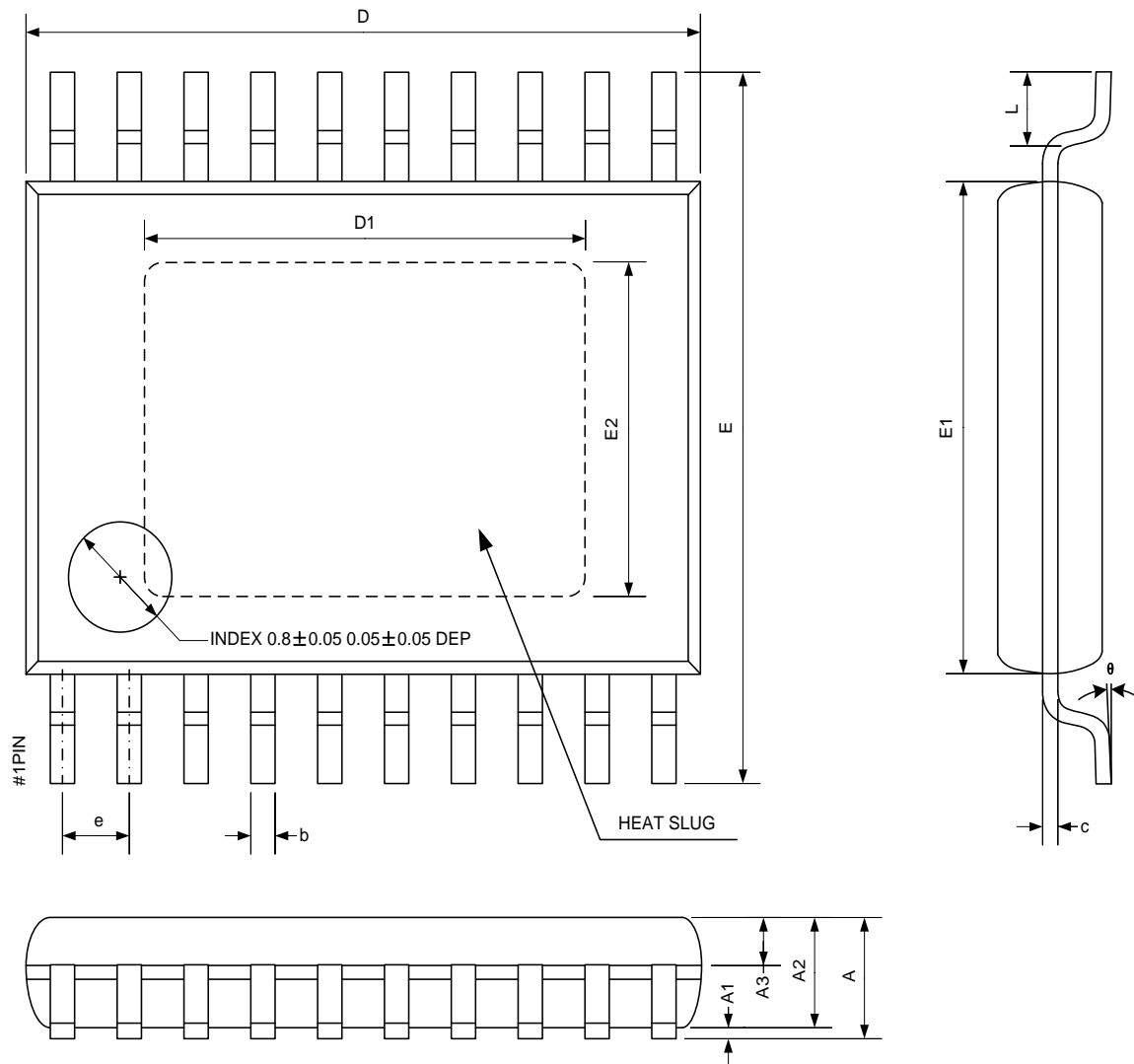
**Figure 46: Dual ft2820 in Tandem for Higher Output Power Applications**

Note: The bold lines are high current paths and their respective traces are required to be as wide and short as possible on the system board for high power applications.



**PHYSICAL DIMENSIONS**

TSSOP-20L PACKAGE OUTLINE DIMENSIONS



SYMBOL	MIN	NOM	MAX	UNIT
A	-	-	1.20	mm
A1	0.05	-	0.15	mm
A2	0.90	1.00	1.05	mm
A3	0.34	0.44	0.54	mm
b	0.20	-	0.28	mm
c	0.10	-	0.19	mm
D	6.40	6.50	6.60	mm
D1	4.00	4.20	4.40	mm
E	6.20	6.40	6.60	mm
E1	4.30	4.40	4.50	mm
E2	2.80	3.00	3.20	mm
e	0.65BSC			mm
L	0.45	0.60	0.75	mm
θ	0	-	8	°

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